

### Amendments to the Claims

1. **(Currently Amended)** A semiconductor device comprising:  
a semiconductor element that has a first surface on which an external connection terminal is formed and a second surface that faces the first surface, and a thickness of 10  $\mu$  m or more and 150  $\mu$  m or less;

a plate that faces the second surface; and  
a resin binder that adheres the second surface and the plate,  
wherein the plate has the rigidity higher than that of the semiconductor element;  
an outer shape of the plate is larger than that of the semiconductor element; and  
the resin binder covers ~~an outer periphery~~ a side face of the semiconductor element, and furthermore at a portion that is interposed between the second surface and the plate the resin binder allows the semiconductor element to deform in a thickness direction thereof.

2. **(Original)** The semiconductor device according to claim 1, wherein the resin binder covers an edge that is formed of a side face and the second surface of the semiconductor element.

3. **(Currently Amended)** The semiconductor device according to claim 1, wherein the resin binder covers the side face over an entire circumference of the semiconductor element.

4. **(Currently Amended)** The semiconductor device according to claim 1, wherein the resin binder covers only a corner of the side face of the semiconductor element.

5. **(Canceled)**

6. **(Original)** The semiconductor device according to claim 1, wherein the external connection terminal is provided with a bump.

7. (Canceled)

8. (Canceled)

9. (Currently Amended) The semiconductor device according to claim 1, wherein the semiconductor element includes a re-wiring layer on the first surface, the re-wiring layer has a surface electrode formed on a surface and an internal electrode formed inside thereof, and the internal electrode connects the surface electrode and the external connection-electrode terminal.

10. (Original) The semiconductor device according to claim 9, wherein the surface electrode is provided with a bump.

11. (Currently Amended) A semiconductor device assembling method in which a semiconductor element and a plate that is higher in the rigidity than the semiconductor element are adhered with a resin binder, the semiconductor element having a first surface on which an external connection terminal is formed and a second surface that faces the first surface, the second surface being adhered to the plate, comprising:

a first step of roughly processing according to mechanical polishing a side opposite to the first surface on which an external connection terminal of the semiconductor element is formed, followed by further applying finishing to obtain a second surface from which a damaged layer is removed and to make a thickness of the semiconductor element 10  $\mu$  m or more and 150  $\mu$  m or less;

a-first second step of supplying the resin binder to a plate member including the plate;

a-second third step of adhering the second surface and the plate in an aligned state with by use of the resin binder; and

a-third fourth step of cutting the plate from the plate member.

12. **(Currently Amended)** The semiconductor device assembling method according to claim 11, wherein in the ~~second~~ third step, the resin binder is formed with an outer periphery of the semiconductor element covered.

13. **(Original)** The semiconductor device assembling method according to claim 12, wherein by use of a decrease in the viscosity of the resin binder owing to heating, the resin binder is spread to a side face of the semiconductor element to cover the outer periphery.

14. **(Currently Amended)** The semiconductor device assembling method according to claim 11, wherein the ~~first~~ second step is a step of supplying a resin binder ~~in~~ by an amount necessary to cover a side face of the semiconductor element.

15. **(Currently Amended)** The semiconductor device assembling method according to claim 11, wherein in the ~~first~~ second step the resin binder supplied is liquid, the plate member has a projection ~~that surrounds~~ surrounding the plate, and the liquid resin ~~binder~~ is supplied inside of the projection.

16. **(Currently Amended)** The semiconductor device assembling method according to claim 11, wherein the resin binder is in sheet, and the ~~first~~ second step is a step of adhering the resin binder sheet to the plate member.

17. **(Currently Amended)** The semiconductor device assembling method according to claim 11, wherein the plate member has a plurality of the plates, and the ~~second~~ third step includes a step of mounting the semiconductor element through the resin binder for each of the plates that the plate member has and a step of heating the plate member on which the semiconductor elements are mounted.

18. **(Currently Amended)** The semiconductor device assembling method according to claim 17, wherein the ~~second~~ third step simultaneously carries out the step of mounting and the step of heating.

19. **(Currently Amended)** The semiconductor device assembling method according to claim 18, wherein the ~~second~~ third step is carried out by use of mounting means of the semiconductor element that are provided with heating means.

20. **(Original)** The semiconductor device assembling method according to claim 11, wherein the semiconductor element has a re-wiring layer on the first surface.